

## PMP10878 REV A Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
!PCB1	1		PMP10878	Any	Printed Circuit Board	<u> </u>
C1	1	2200pF	DE1E3KX222MN5AA01	MuRata	CAP, CERM, 2200 pF, 250 V, +/- 20%, E, 10.0x8.0x14.0mm	10.0x8.0x14.0mm
C2, C11	2	100uF	EEUED2E101S	Panasonic	CAP, AL, 100 μF, 250 V, +/- 20%, 0.243706 ohm, TH	18x25
C3, C6	2	470pF	VY2471K29Y5SS63V7	Vishay-Bccomponents	CAP, CERM, 470pF, 300V, +/-10%, VY2, 5x7.5 mm	5x7.5 mm
C4	1	0.33uF	ECQ-U2A334ML	Panasonic	CAP, Film, 0.33uF, 275V, +/-20%, TH	RCAP,
						17.5x17.5x9.5mm
C7, C8	2	680uF	UHW1V681MPD6	Nichicon	CAP ALUM 680UF 35V 20% RADIAL	CAPPR5-10x16
C9	1	680uF	35ZLJ680M10X25	Rubycon	CAP ALUM 680UF 35V 20% RADIAL	CAPPR5-10x16
C10	1	0.1uF	C1206C104J5RACTU	Kemet	CAP, CERM, 0.1 µF, 50 V, +/- 5%, X7R, 1206	1206
C12	1	2.2uF	12063D225KAT2A	AVX	CAP, CERM, 2.2 µF, 25 V, +/- 10%, X5R, 1206	1206
C13, C23	2	1uF	C0603C105K4PACTU	Kemet	CAP, CERM, 1 µF, 16 V, +/- 10%, X5R, 0603	0603
C14	1	0.01uF	C1608X8R1H103K	TDK	CAP, CERM, 0.01 µF, 50 V, +/- 10%, X8R, 0603	0603
C15	1	1000uF	UHW1C102MPD	Nichicon	CAP, AL, 1000uF, 16V, +/-20%, TH	CAPPR5-10x16
C16, C24	2	0.1uF	GRM155R61C104KA88D	MuRata	CAP, CERM, 0.1 µF, 16 V, +/- 10%, X5R, 0402	0402
C17, C18, C29,	4	22uF	GRM21BR60J226ME39L	MuRata	CAP, CERM, 22 µF, 6.3 V, +/- 20%, X5R, 0805	0805
C30						
C19, C35	2	22uF	C2012X5R1C226K125AC	TDK	CAP, CERM, 22uF, 16V, +/-10%, X5R, 0805	0805
C20, C32	2	22uF	CL32A226KAJNNNE	Samsung	CAP, CERM, 22 μF, 25 V, +/- 10%, X5R, 1210	1210
C21, C33	2	0.1uF	0603YC104JAT2A	AVX	CAP, CERM, 0.1 μF, 16 V, +/- 5%, X7R, 0603	0603
C22, C34	2	0.01uF	06031C103MAT2A	AVX	CAP, CERM, 0.01 µF, 100 V, +/- 20%, X7R, 0603	0603
C26	1	0.1uF	06035C104KAT2A	AVX	CAP, CERM, 0.1uF, 50V, +/-10%, X7R, 0603	0603
C27, C28	2	2.2uF	GRM31CR61H225KA88L	MuRata	CAP, CERM, 2.2uF, 50V, +/-10%, X5R, 1206	1206
C31, C36	2	1uF	C1005X5R1E105K050BC	TDK	CAP, CERM, 1uF, 25V, +/-10%, X5R, 0402	0402
D1	1	100V	MBRB20100CTT4G	ON Semiconductor	Diode, Schottky, 100 V, 20 A, DDPAK	DDPAK
D2, D5	2	600V	1N5406	Vishay-Semiconductor	Diode, Switching-Bridge, 600 V, 3 A, TH	DO-201AD
D3	1	160V	SMBJ160A-13-F	Diodes Inc.	Diode, TVS, Uni, 160 V, 600 W, SMB	SMB
D4	1	1.7V	US1M-13-F	Diodes Inc.	Diode, Ultrafast, 1000V, 1A, SMA	SMA
D6	1	60V	B360-13-F	Diodes Inc.	Diode, Schottky, 60 V, 3 A, SMC	SMC
D7	1		BAS20HT1G		DIODE SWITCH 200V 200MA SOD323	SOD-323
F1	1		37012000410	Littelfuse	FUSE FAST 250VAC 2A RADIAL	TR5 fuse 8.5mm DIA
H1	1		507302B00000G	Aavid	Heat Sink, TO-220	TO-220 Heat Sink
J1	1		1-1318301-3	TE Connectivity	Header, 312mil, 3x1, Tin, TH	19.7x10.7 x8.5 mm
J2, J3	2	2x1	1715721	Phoenix Contact	Conn Term Block, 2POS, 5.08mm, TH	2POS Terminal Block
J4, J5	2		292303-4	TE Connectivity	Connector, Receptacle, USB Type A, R/A, Top Mount TH	USB Type A right
				,		angle
L1	1	10mH	744823210	Wurth Elektronik eiSos	Coupled inductor, 10 mH, 2 A, 0.125 ohm, +/- 30%, TH	13x22x17.5mm
L2	1	2.2uH	74438322022	Wurth Elektronik eiSos	FIXED IND 2.2UH 1.34A 302 MOHM	SMD, 2.5x2mm
L3	1	4.7uH	74437324047	Wurth Elektronik eiSos	Inductor, Shielded Drum Core, Powdered Iron, 4.7 µH, 2.2 A, 0.095 ohm,	Inductor,
					SMD	4.06x2x4.06mm
Q1	1	800V	SPA04N80C3	Infineon Technologies	MOSFET N-CH 800V 4A TO220FP	TO-220 FullPAK
R1, R2, R4, R6	4	1.0Meg	CRCW12061M00JNEA	Vishay-Dale	RES, 1.0 M, 5%, 0.25 W, 1206	1206
R5	1	7.5k	CRCW12067K50JNEA	Vishay-Dale	RES, 7.5 k, 5%, 0.25 W, 1206	1206
R7	1	33.2	CRCW120633R2FKEA	Vishay-Dale	RES, 33.2 ohm, 1%, 0.25W, 1206	1206
R8	1	0	CRCW06030000Z0EA	Vishay-Dale	RES, 0, 5%, 0.1 W, 0603	0603
R9	1	4.7	CRCW12064R70JNEA	Vishay-Dale	RES, 4.7 ohm, 5%, 0.25W, 1206	1206
R10, R17	2	10.0k	CRCW060310K0FKEA	Vishay-Dale	RES, 10.0 k, 1%, 0.1 W, 0603	0603
R11	1	86.6k	CRCW060386K6FKEA	Vishay-Dale	RES, 86.6 k, 1%, 0.1 W, 0603	0603
R12	1	73.2k	CRCW060373K2FKEA	Vishav-Dale	RES, 73.2 k, 1%, 0.1 W, 0603	0603
R13, R14	2	3.3Meg	CRCW08053M30JNEA	Vishay-Dale	RES, 3.3Meg ohm, 5%, 0.125W, 0805	0805
R15, R22	2	22.1k	CRCW060322K1FKEA	Vishay-Dale	RES, 22.1 k, 1%, 0.1 W, 0603	0603
R16	1	0	CRCW06030000Z0EA	Vishay-Dale Page	RES, 0 ohm, 5%, 0.1W, 0603	0603

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R18	1	910	CRCW1206910RJNEA	Vishay-Dale	RES, 910, 5%, 0.25 W, 1206	1206
R19	1	121k	CRCW0603121KFKEA	Vishay-Dale	RES, 121 k, 1%, 0.1 W, 0603	0603
R20	1	0.25	ERJ-12ZQJR39U	Panasonics	RES SMD 0.39 OHM 5% 1/2W 2010	2010
R21	1	23.7k	CRCW060323K7FKEA	Vishay-Dale	RES, 23.7 k, 1%, 0.1 W, 0603	0603
R23	1	41.2k	CRCW040241K2FKED	Vishay-Dale	RES, 41.2 k, 1%, 0.063 W, 0402	0402
R24	1	73.2k	CRCW040273K2FKED	Vishay-Dale	RES, 73.2 k, 1%, 0.063 W, 0402	0402
RT1	1	10 ohm	B57236S0100M000	EPCOS Inc	Thermistor NTC, 10 ohm, 20%, Disc_11.5mmx6mm	Disc_11.5mmx6mm
T1	1	350 uH	750315307	Wurth Elektronik eiSos	Transformer, 350 uH, TH	32.25x27.05mm
TP1, TP3, TP5	3	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature
						Testpoint
TP2, TP4, TP6	3	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature
						Testpoint
U1	1		LP2985-10DBVR	Texas Instruments	Micropower 150 mA Low-Noise Ultra Low-Dropout Regulator, 5-pin SOT-	MF05A
					23	
U2	1		TPS542951PWPR	Texas Instruments	IC REG BUCK ADJ 2/3A 16HTSSOP	PWP0016C
U3	1		UCC28700DBV	Texas Instruments	Constant-Voltage, Constant-Current Controller With Primary-Side	DBV0006A
					Regulation, DBV0006A	
U4, U5	2		TPS2511DGN	Texas Instruments	USMB Dedicated Charging Port Controller and Current Limiting Power	DGN0008E
					Switch, DGN0008E	
C5	0	100pF	C1608C0G2A101J	TDK	CAP, CERM, 100pF, 100V, +/-5%, C0G/NP0, 0603	0603
C25	0	2.2pF	06035A2R2CAT2A	AVX	CAP, CERM, 2.2 pF, 50 V, +/- 11%, C0G/NP0, 0603	0603
R3	0	DNP	CRCW08050000Z0EA	Vishay-Dale	RES, 0 ohm, 5%, 0.125W, 0805	0805

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